

AMAT Etch Centura

Etch centura is a cluster tool for reactive etching and resist ashing in a state of the art 8 inch CMOS manufacturing process. RIE of the target stack and resist ashing can be done without vacuum break. The tool currently has two process chambers: one for RIE and the other for resist ashing.

Process Capabilities:

- **Wafer Size:** 8 inches.
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- **Gases:** O₂, N₂, SF₆, BCl₃, Cl₂, CHF₃
- **Etch chamber:**
Applications: Gate stack etching
- **Resist Asher:**
Application: Resist ashing in oxygen plasma

